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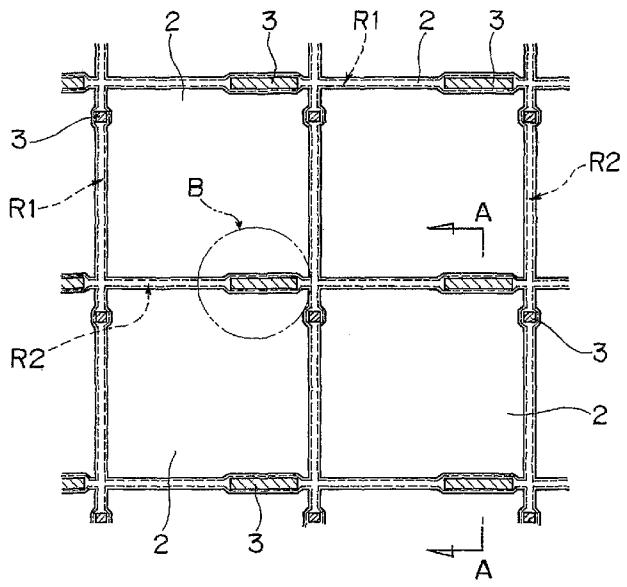
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(54) Title: MANUFACTURING METHOD FOR SEMICONDUCTOR CHIPS AND SEMICONDUCTOR WAFER



(57) Abstract: In a semiconductor wafer that has semiconductor devices arranged in a plurality of device-formation-regions and a TEG placed in dividing regions that define the device-formation-regions, a TEG-placement portion is arranged in the dividing regions partially expanded in width, and the TEG is placed in the TEG-placement portion. And, a protective sheet is stuck to the semiconductor wafer, then plasma etching is performed, and the TEG in a state where it remains in the dividing region and stuck to the protective sheet is removed together with the protective sheet by peeling off the protective sheet, thereby the device-formation-regions are divided into individual pieces, and the semiconductor chips are manufactured.

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